

PRODUCTS Semiconductor IC TYPE BA178XXFP

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STRUCTURE

Silicon Monolithic Integrated Circuit

TYPE

Three-Terminal Regulator

PRODUCT SERIES

BA178XXFP

FEATURE

Output current up to 1A

OABSOLUTE MAXIMUM RATING (Ta=25°C)

Parameter	Symbol	Limit	Unit
Input Voltage	Vin	35	V
Power Dissipation 1	Pd1	1*1	W
Power Dissipation 2	Pd2	10* ²	W
Output Current	lout	1*3	Α
Operating Temperature Range	Topr	-40~+85	°C
Storage Temperature Range	Tstg	-55~+150	°C
Maximum Junction Temperature	Tjmax	150	°C

^{*1} Derating in done 8mW/°C for temperatures above Ta=25°C.

ORECOMMENDED OPERATING CONDITIONS (Ta=-40~+85°C)

Parameter	Symbol	Туре	Min	Max	Unit
	BA17805FP	7.5	25		
		BA17806FP	8.5	21	
		BA17807FP	9.5	22	
		BA17808FP	10.5	23	
		BA17809FP	11.5	26	
Input Voltage Vin	BA17810FP	12.5	25	٧	
		BA17812FP	15	27	
		BA17815FP	17.5	30	
		BA17818FP	21	33	
	BA17820FP BA17824FP	23	33		
		BA17824FP	27	33	
Output Current	lo	Common	_	1* ³	Α

The product described in this specification is a strategic product (and/or Service) subject to COCOM regulations.

It should not be exported without Authorization from the appropriate government.

This product is not designed for protection against radioactive rays.

Status of this document

The Japanese version of this document is the formal specification. A customer may use this translation version only for a reference to help reading the formal version. If there are any differences in translation version of this document, formal version takes priority.

Application example

ROHM cannot provide adequate confirmation of patents.

The product described in this specification is designed to be used with ordinary electronic equipment or devices (such as audio-visual equipment, office-automation equipment, communications devices, electrical appliances, and electronic toys).

Should you intend to use this product with equipment or devices which require an extremely high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, serospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.

• ROHM assumes no responsibility for use of any circuits described herein, conveys no license under any patent or other right, and makes no representations that the circuits are free from patent infringement.

	DESIGN	CHECK	APPROVAL	DATE:	Apr/22/*05	SPECIFICATION No. : TSZ02201-BA178XXFP-1-2
[9-10		Junopash	REV.	В	ROHM CO., LTD.

^{*2} Derating in done 80mW/°C for temperatures above Ta=25°C, Mounted on 50mm × 50mm × 2.0mm Alminium heat sink

^{*3} Pd, ASO should not be exceeded.



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OELECTRICAL CHARACTERISTICS

(Unless otherwise specified ,Ta=25°C,Vin=10V(05),11V(06),13V(07),14V(08),15V(09),16V(10),19V(12),23V(15),27V(18),29V(20),33V(24), lo=500mA)

Parameter	Symbol	Туре	Min.	Limit Typ.	Max.	Unit	Condition
	\longrightarrow	05	4.8	5.0	5.2		
	!		5.75		6.25		
	1 F	06 07	6.7	7.0	7.3		
	1 F	07	7.7	8.0	8.3		
	\ 	08	8.6	9.0	9.4		
Output Voitage1	Vo1		9.6		10.4	٧	I o=500mA
Juput Voltage 1	101	10	11.5	10.0 12.0	12.5	•	- 5 - 5551117
	1 F	12	14.4	12.0 15.0	15.6		
	1 -	18	17.3	18.0	18.7		
	1 F	20	19.2	20.0	20.8		
	1	24	23.0	24.0	25.0		
	+	05	4.75	-	5.25		Vin=7.5~20V, lo=5mA~1A
· ·	(F	06	5.7		6.3		Vin=8.5~21V, lo=5mA~1A
ı	1 F	07	6.65	_	7.35		Vin=9.5~22V, lo=5mA~1A
	1 1	08	7.6	_	8.4		Vin=10.5~23V, lo=5mA~1/
	l l	09	8.55	_	9.45		Vin=10.5~26V, lo=5mA~1/
Output Voltage2	Vo2	10	9.5	_	10.5	V	Vin=12.5~25V, lo=5mA~1/
	1 - F	12	11.4	_	12.6	-	Vin=15~27V, lo=5mA~1A
	Į ŀ	15	14.25		15.75		Vin=17.5~30V, lo=5mA~1
	<u> </u>	18	17.1		18.9		Vin=21~33V, lo=5mA~1A
	1 1	20	19.0	_	21.0		Vin=23~33V, lo=5mA~1A
	Į ŀ	24	22.8	_	25.2		Vin=27~33V, lo=5mA~1A
		05	_	3	100		Vin=7~25V, lo=500mA
	1 1	06	_	4	120		Vin=8~25V, lo=500mA
		07	_	5	140		Vin=9~25V, lo=500mA
		08	_	5	160		Vin=10.5~25V, lo=500mA
	h	09	_	6	180		Vin=11.5~26V, lo=500mA
Line Regulation1	Reg.l1	10	_	7	200	mV	Vin=12.5~27V, lo=500mA
J		12	_	8	240		Vin=14.5~30V, lo=500mA
		15		9	300		Vin=17.5~30V, lo=500mA
		18	_	10	360		Vin=21~33V, lo=500mA
		20		12	400		Vin=23~33V, lo=500mA
		24		15	480		Vin=27~33V, lo=500mA
		05	-	1	50		Vin=8~12V, lo=500mA
		06		2	60		Vin=9~13V, lo=500mA
		07		2	70		Vin=10~15V, lo=500mA
		08		3	80		Vin=11~17V, lo=500mA
		09		4	90		Vin=13~19V, lo=500mA
Line Regulation2	Reg.l2	10		4	100	mV	Vin=14~20V, lo=500mA
		12		5	120		Vin=16~22V, lo=500mA
		15	_	5	150		Vin=20~26V, lo=500mA
		18	_	5	180		Vin=24~30V, lo=500mA
		20		7	200		Vin=26~32V, lo=500mA
		24		10	240		Vin=30~33V, lo=500mA
		05	62	78	_		
		06	59	73			
		07	57	69			
		08	56	65		1	
		09	56	64	<u> </u>		ein=1Vrms, f=120Hz,
Ripple Rejection	R.R.	10	55	64		dB	Io=100mA
		12	55	63		1	
	1	15	54 55	62		1	
		18	55 53	61	 - -	1	
		20			 -	1	
	+	24	50	58	╄	-	
Temperature		05		-1.0	 	1	
Coefficient of	Tcvo	06/07/08/09/10/12 15/18	 	-0.5 -0.6	 	mV/°C	lo=5mA, Tj=0~125°C
Output Voltage		15/18			+	1	
			I –	-0.7	I –	1	i

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	Symbol	Туре	Min.	Limit Typ.	Max.	Unit	Condition
		05	- IVIII 1.	1yp.	100		<u> </u>
		06		16	120		
		07	_		140		
				17			
		08		19	160		
		09		20	180		
Load Regulation1	Reg.L1	10		21	200	mV	lo=5mA~1A
1	-	12		23	240		
		15		27	300		
	ļ	18		30	360		
		20		32	400		
		24		37	480	· · · · · · · · · · · · · · · · · · ·	
l		05	_	5	50		
		06		6	60		
		07	_	6	70		
		08	_	7	80		Ì
		09	-	8	90		
Load Regulation2	Reg.L2	10	-	8	90	mV	lo=250mA~750mA
		12	_	10	120		
		15	_	10	150		
		18	_	12	180		1
	i	20	_	14	200		
		24	_	15	240		
	***	05	-	40	_		<u> </u>
		06		60	_		
	Vn	07	_	70			
Ì		08	_	80			
Outrut Nains		09		90	_		
Output Noise Voltage		10	_	100	. –	μV	f=10Hz~100kHz
· · · · · · · · · · · · · · · · · · ·		12	_	110	_		
		15	_	125	_		
		. 18	_	140	_		
		20	-	150	_]	
		24		180			
Dropout Voltage	Vd	Common		2.0		V	lo=1A
Bias Current	lb	Common	_	4.5	8.0	mA	lo=0mA
Bias Current Change 1	lb1	Common			0.5	mA	lo=5mA~1A
		05	_		0.8		Vin:8~25V, lo=500mA
		06 07			0.8		Vin:8.5~25V, lo=500mA
		08			0.8		Vin:9.5~25V, lo=500mA
		09		=	0.8		Vin:10.5~25V, lo=500mA Vin:11.5~26V, lo=500mA
Bias Current Change 2	lb2	10	_	-	0.8	mA	Vin:12.5~27V, lo=500mA
		12			0.8		Vin:14.5~30V, lo=500mA
		15	-		0.8		Vin:17.5~30V, lo=500mA
		18	_		0.8		Vin:21~33V, lo=500mA
		20	_	_	0.8		Vin:23~33V, lo=500mA
		24	-	_	0.8		Vin:27~33V, lo=500mA
		0.000.000.000	_	0.6	-	Λ	Vin=25V
Short-Circuit	lee	05/06/07/08		_		Α	
Short-Circuit Output Current	los	05/06/07/08 09/10/12/15/18/20/24	_	0.3	_		Vin=30V
	los	09/10/12/15/18/20/24 05	_	9			VIN=30V
	los	09/10/12/15/18/20/24 05 06/07/08/09		9 10	 		VIN=30V
	los	09/10/12/15/18/20/24 05 06/07/08/09 10	_	9 10 11			VIN=30V
Output Current		09/10/12/15/18/20/24 05 06/07/08/09 10 12		9 10 11 12	-	mO	
	los	09/10/12/15/18/20/24 05 06/07/08/09 10 12 15	- - - -	9 10 11 12 14	_ _ _ _ _	mΩ	f=1kHz
Output Current		09/10/12/15/18/20/24 05 06/07/08/09 10 12	- - -	9 10 11 12	- - -	mΩ	

O Output Voltage and Marking

Туре	Marking	Output Voltage(V)
BA17805FP	17805	5
BA17806FP	17806	6
BA17807FP	17807	7
BA17808FP	17808	8
BA17809FP	17809	9
BA17810FP	17810	10

Туре	Marking	Output Voltage(V)
BA17812FP	17812	12
BA17815FP	17815	15
BA17818FP	17818	18
BA17820FP	17820	20
BA17824FP	17824	24

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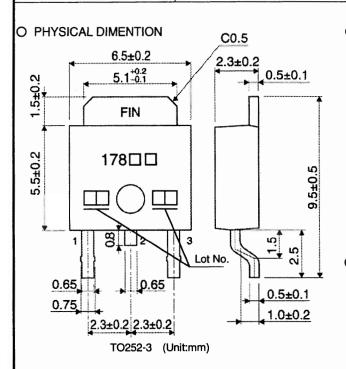
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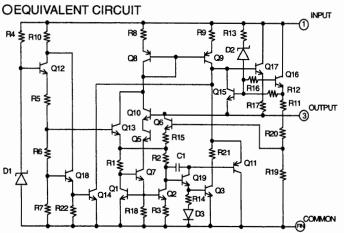
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TYPE





OPin number, Pin name

Pin number	Pin name
1	INPUT
2	N.C.
3	OUTPUT
FIN	COMMON

O NOTES FOR USE

(1) Absolute maximum range

We are careful enough for quality control about this IC. So, there is no problem under normal operation, excluding that it exceeds the absolute maximum ratings. However, Absolute Maximum Ratings are those values beyond which the life of a device may be destroyed we cannot be defined the failure mode, such as short mode or open mode. Therefore physical security countermeasure, like fuse, is to be given when a specific mode to be beyond absolute maximum ratings is considered.

(2) Ground voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.

(3) Thermal design

When you do the kind of use which exceeds Pd, It may be happened to deteriorating IC original quality such as decrease of electric current ability with chip temperature rise. Do not exceed the power dissipation (Pd) of the package specification rating under actual operation, and please design enough temperature margins.

- (4) Short circuit mode between terminals and wrong mounting
 - Do not mount the IC in the wrong direction and be careful about the reverse-connection of the power connector. Moreover, this IC might be destroyed when the dust short the terminals between them or GND.
- (5) Operation in the strong electromagnetic field

Malfunction may be happened when the device is used in the strong electromagnetic field.

(6) ASO

Do not exceed the maximum ASO and the absolute maximum ratings of the output transistor.

(7) Thermal shutdown circuit

The thermal shutdown circuit (TSD circuit) is built in this product. When IC chip temperature become higher, the thermal shutdown circuit operates and turns output off. The thermal shutdown circuit, which is aimed at isolating the LSI from thermal runaway as much as possible, is not aimed at the protection or guarantee of the LSI. Therefore, do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.

(8) GND wiring pattern

Use separate ground lines for control signals and high current power driver outputs. Because these high current outputs that flows to the wire impedance changes the GND voltage for control signal. Therefore, each ground terminal of IC must be connected at the one point on the set circuit board. As for GND of external parts, it is similar to the above-mentioned.

- (9) Internal circuits could be damaged if there are modes in which the electric potential of the application's input and GND are the opposite of the electric potential of the various outputs. Use of a diode or other such bypass is recommended.
- (10) We recommend to put Diode for protection purpose in case of output pin connected with large load of impedance or reserve current occurred at initial and output off.

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Notice

Precaution on using ROHM Products

Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CI ACCIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
 - [a] Installation of protection circuits or other protective devices to improve system safety
 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
- 3. Our Products are designed and manufactured for use under standard conditions and not under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

When disposing Products please dispose them properly using an authorized industry waste company.

Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

Precaution Regarding Intellectual Property Rights

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